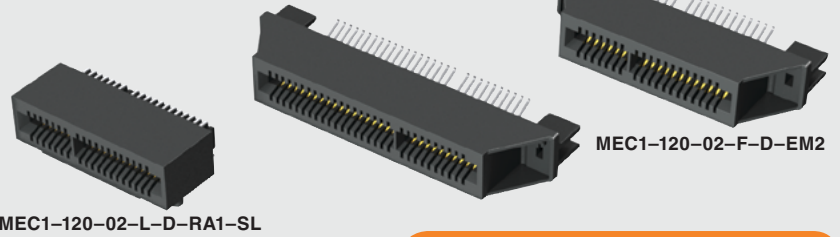


MEC1-130-02-L-D-EM2



MEC1-120-02-F-D-EM2

MEC1-120-02-L-D-RA1-SL

MEC1-RA, MEC1-EM SERIES

(1.00 mm) .0394"

# RIGHT-ANGLE/EDGE MOUNT SOCKETS

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC1-RA](http://www.samtec.com?MEC1-RA)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50 μ" (1.27 μm) Ni  
**Current Rating:** 1.6 A per pin (2 adjacent pins powered)  
**Operating Temp Range:** -55 °C to +125 °C  
**Insertion Depth:** (5.84 mm) .230" to (8.13 mm) .320"  
**RoHS Compliant:** Yes

## PROCESSING

**Lead-Free Solderable:** Yes  
**SMT Lead Coplanarity:** (0.10 mm) .004" max (05-40) (0.15 mm) .006" max (50-70)\*  
 \*(.004" stencil solution may be available; contact IPG@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**MEC1** - **1** POSITIONS PER ROW - **CARD SLOT** - **PLATING OPTION** - **D** - **RA1** - **NP** - **SL**

Mates with:  
 (1.60 mm)  
 .062" card

05, 08, 20, 30,  
 40, 50, 60, 70

-02  
 = (1.60 mm)  
 .062" thick card

-F  
 = Gold flash on contact,  
 Matte Tin on tail

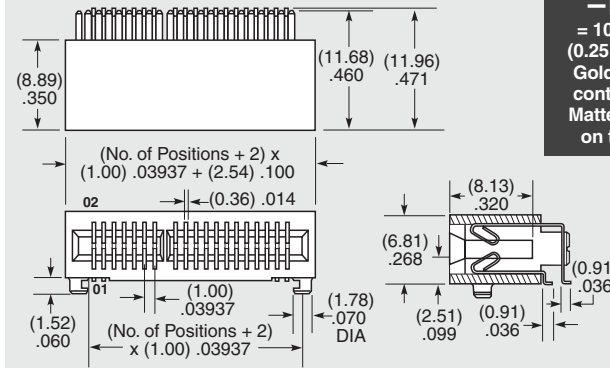
-L  
 = 10 μ" (0.25 μm)  
 Gold on contact,  
 Matte Tin on tail

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

-NP  
 = No Polarization  
 (8 positions only)  
 Leave Blank for polarization

**ALSO AVAILABLE (MOQ Required)**

- Elevated body height
- Other platings



Note: Some sizes, styles and options are non-standard, non-returnable.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

## HIGH-SPEED CHANNEL PERFORMANCE

MEC1-RA

Rating based on Samtec reference channel.  
 For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

14  
 G b p s

## APPLICATION

Samtec recommends that pads on the mating board be Gold plated.

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC1-EM](http://www.samtec.com?MEC1-EM)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze  
**Plating:** Au or Sn over 50 μ" (1.27 μm) Ni  
**Current Rating:** 1.8 A per pin (2 adjacent pins powered)  
**Operating Temp Range:** -55 °C to +125 °C  
**Insertion Depth:** (5.84 mm) .230" to (8.13 mm) .320"  
**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**MEC1** - **1** POSITIONS PER ROW - **02** - **PLATING OPTION** - **D** - **EM2** - **NP**

Mates with:  
 (1.60 mm)  
 .062" card

05, 08, 20, 30,  
 40, 50, 60, 70

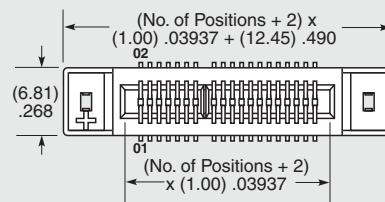
-F  
 = Gold flash on contact,  
 Matte Tin on tail

-L  
 = 10 μ" (0.25 μm) Gold on contact,  
 Matte Tin on tail

-NP  
 = No Polarization  
 (8 positions only)  
 Leave Blank for polarization

**ALSO AVAILABLE (MOQ Required)**

- Edge mount leads for (0.80 mm) .031" thick board
- Other platings



Note: Some sizes, styles and options are non-standard, non-returnable.

Note: While optimized for 50 Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75 Ω applications.

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

Due to technical progress, all designs, specifications and components are subject to change without notice.